

**SPECIFICATION:**

**MATERIAL**

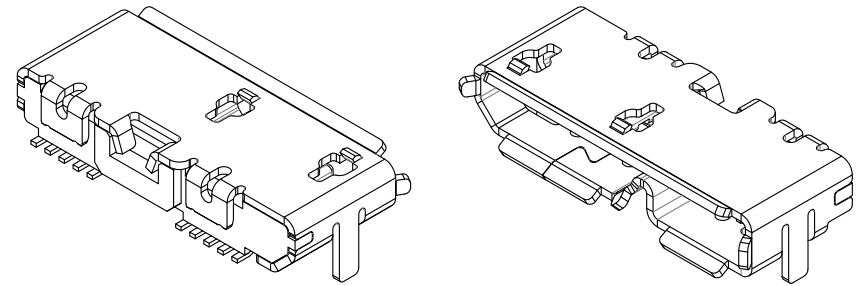
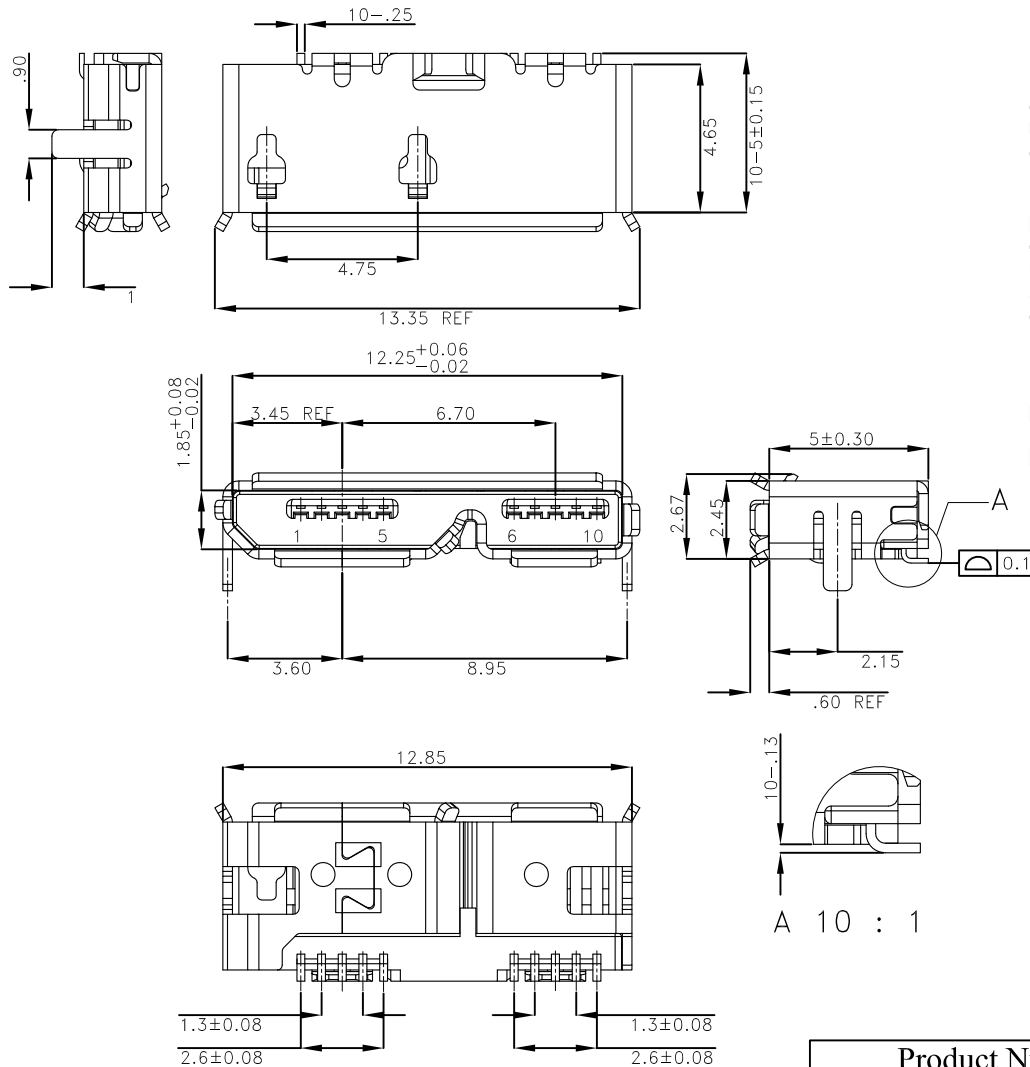
Insulator: Thermoplastic, rated UL94V-0  
 Contacts: Copper Alloy  
 Shell: Stainless Steel

**CONTACT PLATING**

Underplate: 50u"~100u" Nickel  
 Contact area: 15u" Gold  
 Solder tails area: 100u"~200u" Tin/Lead Free(Matte)

**ELECTRICAL**

Current rating:  
 1.8 Amps (max) shall be applied to Vbus pin and its corresponding GND Pin.  
 0.25 Amp (Min) shall be applied to all the other contacts.  
 Contact resistance:  
 30 mΩ (Max) initial for VBUS and GND Contacts.  
 50 mΩ (Max) initial for All Other Contacts.  
 Insulation resistance: 100 Mohms min @ 250 VDC  
 Dielectric withstanding voltage: 100 VAC / minute  
 Temperature range: -20°C TO +85°C  
 Mating cycles: 10,000 insertions



<b>Product Number</b>	<b>Description</b>
209E-BE01	Micro USB 3.0 B Receptacle, Shell:Dip Type , 15u" Gold Plating

UNLESS OTHERWISE SPECIFIED TOLERANCE		
ANGLES	ANG.	±5°
LINEAR	0.	±0.3
	0.0	±0.25
	0.00	±0.20
SCALE	AS SHOWN	UNIT: mm
DRAWN	Willis	2012/08/03
CHECKED	Angel	2012/08/03
APPROVED	Ken	2012/08/03

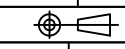


www.attend.com.tw	
DRAWN NAME: Micro USB3.0 B Receptacle Solder Tail;SMD Type, Shell:Dip Type	
PRODUCT NO.	209E-BE01
FILE NAME	209E-BE01_B_2

REV.	DESCRIPTION	DATE	REV.	DESCRIPTION	DATE
1			4		
2			5		
3			6		
4			7		

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 △ Revise:  
 △ Revise:  
 △ Revise:

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SIZE A4 REV. 1.0

